

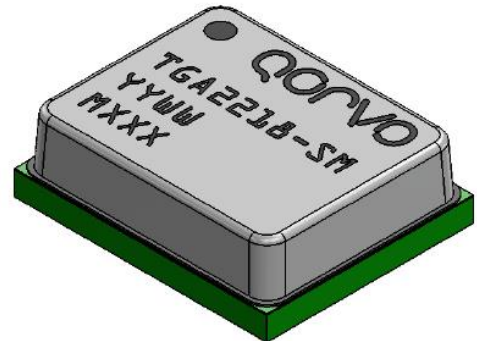
Product Overview

Qorvo's TGA2218-SM is a packaged Ku-band, high power MMIC amplifier fabricated on Qorvo's production 0.15 μm GaN on SiC process. The TGA2218-SM operates from 13.4–16.5 GHz and provides greater than 12 W of saturated output power with 23 dB of large signal gain and greater than 29% power-added efficiency.

This high performance combination provides system designers the flexibility to improve system performance while reducing size and cost.

The TGA2218-SM is fully matched to 50 Ohms with integrated DC blocking capacitors on the RF ports simplifying system integration. It is ideally suited for military and commercial Ku-band radar and satellite communication systems.

Lead-free and RoHS compliant.



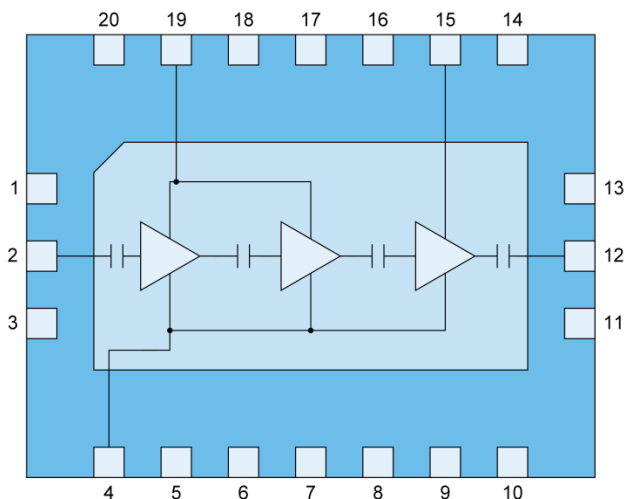
Key Features

- Frequency Range: 13.4–16.5 GHz
- P_{SAT} : > 41 dBm (P_{IN} = 18 dBm)
- PAE: > 29% (P_{IN} = 18 dBm)
- Large Signal Gain: > 23 dB
- Small Signal Gain: > 28 dB
- Bias: V_D = 28 V, I_{DQ} = 225 mA, V_G = -2.6 V Typical
- Package Dimensions: 5.50 x 4.50 x 1.67 mm

Applications

- Satellite Communications
- Data Link
- Radar

Functional Block Diagram



Ordering Information

| Part No. | Description |
|----------------|--|
| TGA2218-SM | 13.4–16.5 GHz 12 W GaN Power Amplifier |
| TGA2218-SM EVB | Evaluation Board |

Absolute Maximum Ratings

| Parameter | Value/Range |
|--|--------------------|
| Drain Voltage (V_D) | 29.5 V |
| Gate Voltage Range (V_G) | -8 to 0 V |
| Drain Current (I_{D12}) | 1.15 A |
| Drain Current (I_{D3}) | 1.03 A |
| Gate Current | See plot on page 3 |
| Power Dissipation (P_{DISS}), 85 °C, CW | 35 W |
| Input Power (P_{IN}), CW, 50 Ω , $V_D = 28$ V, $I_{DQ} = 225$ mA, 85 °C | 30 dBm |
| Input Power (P_{IN}), CW, VSWR 3:1, $V_D = 28$ V, $I_{DQ} = 225$ mA, 85 °C | 27 dBm |
| Mounting Temperature (30 seconds) | 260 °C |
| Storage Temperature | -40°C to 150 °C |

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied

Recommended Operating Conditions

| Parameter | Value/Range |
|----------------------------|----------------|
| Drain Voltage (V_D) | 28 V |
| Drain Current (I_{DQ}) | 225 mA (Total) |
| Gate Voltage (V_G) | -2.6 V (Typ.) |

Electrical Specifications

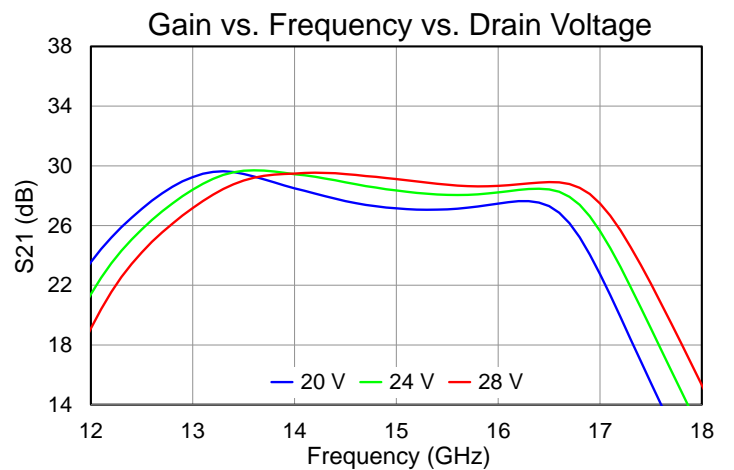
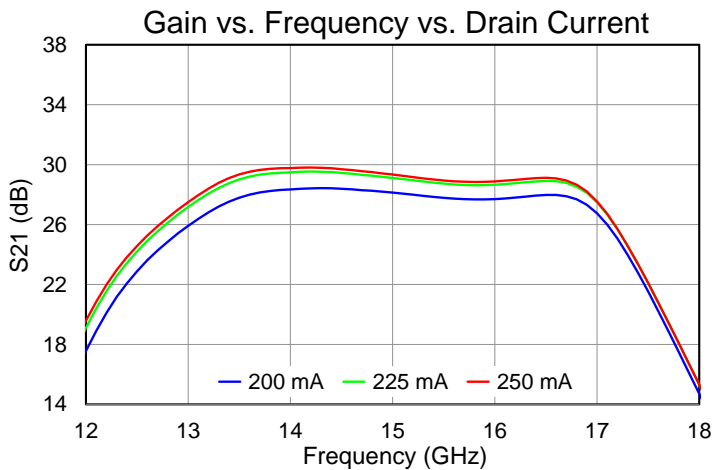
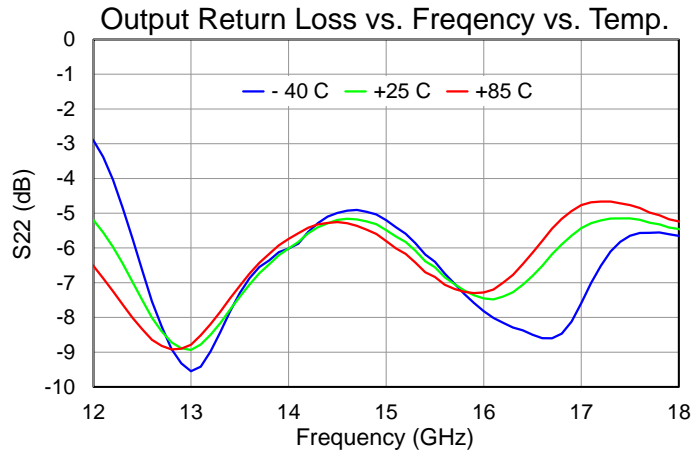
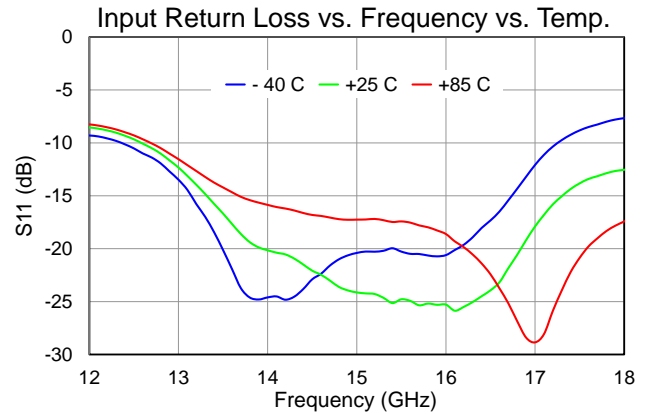
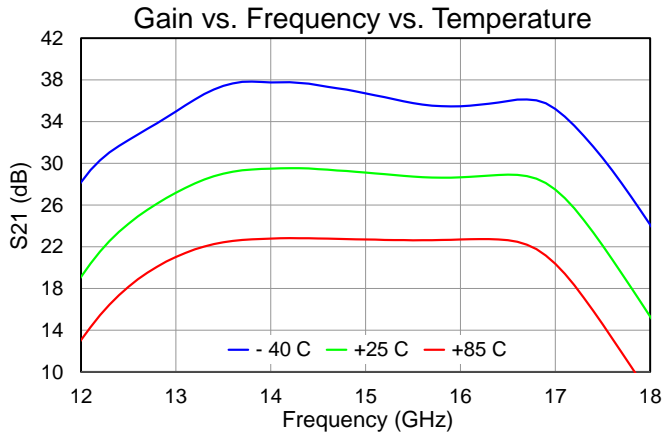
Test conditions unless otherwise noted: 25 °C, $V_D = 28$ V, $I_{DQ} = 225$ mA, $V_G = -2.6$ V Typical, CW

| Parameter | Min | Type | Max | Units |
|--|------|----------|------|-------|
| Operational Frequency Range | 13.4 | | 16.5 | GHz |
| Small Signal Gain | | > 28 | | dB |
| Input Return Loss | | > 15 | | dB |
| Output Return Loss | | > 5 | | dB |
| Power Gain ($P_{IN} = 18$ dBm) | | > 23 | | dB |
| Output Power ($P_{IN} = 18$ dBm) | | > 41 | | dBm |
| Power Added Efficiency ($P_{IN} = 18$ dBm) | | > 29 | | % |
| Small Signal Gain Temperature Coefficient | | -0.11 | | dB/°C |
| Output Power Temperature Coefficient (Temp: 25 °C – 85 °C @ $P_{IN} = 18$ dBm) | | -0.01 | | dB/°C |
| Recommended Operating Voltage | | 20 to 28 | 28 | V |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

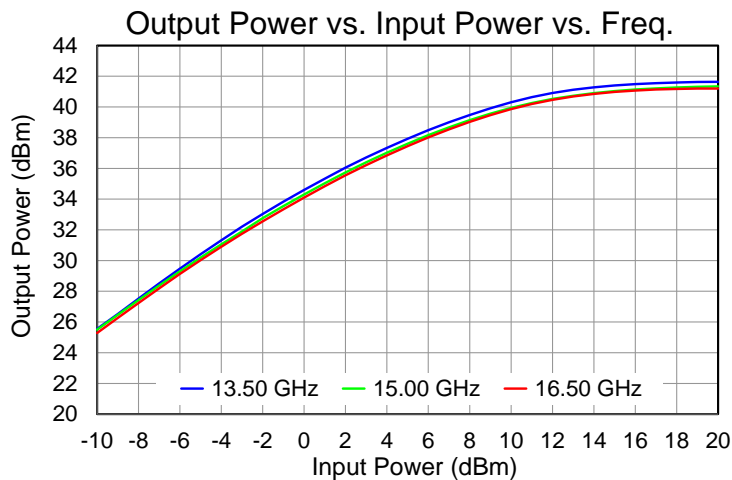
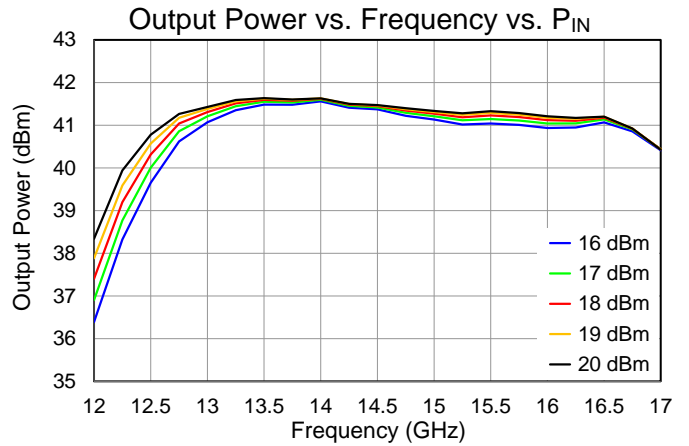
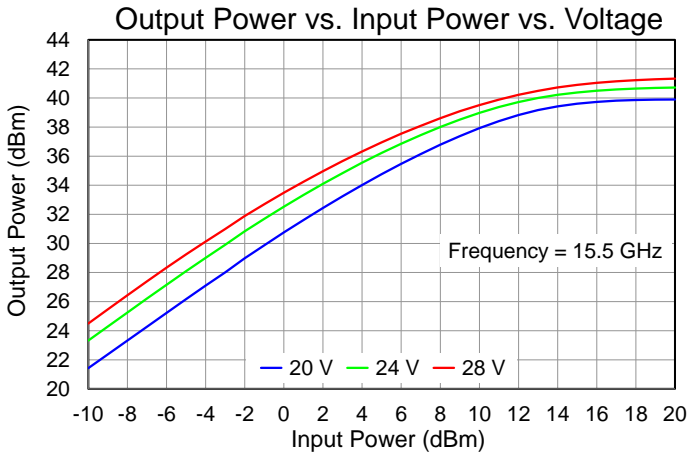
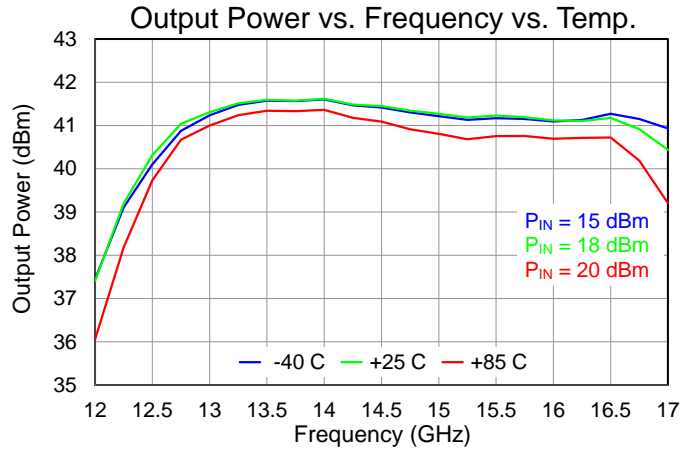
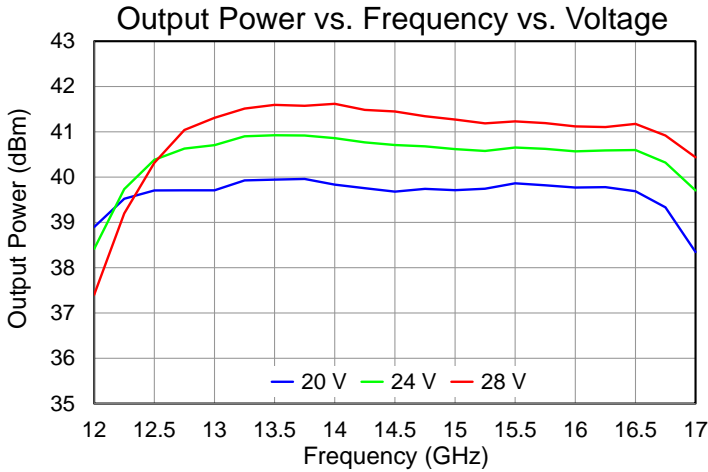
Typical Performance: Small Signal

Test conditions unless otherwise noted: 25 °C, $V_D = 28\text{ V}$, $I_{DQ} = 225\text{ mA}$, CW



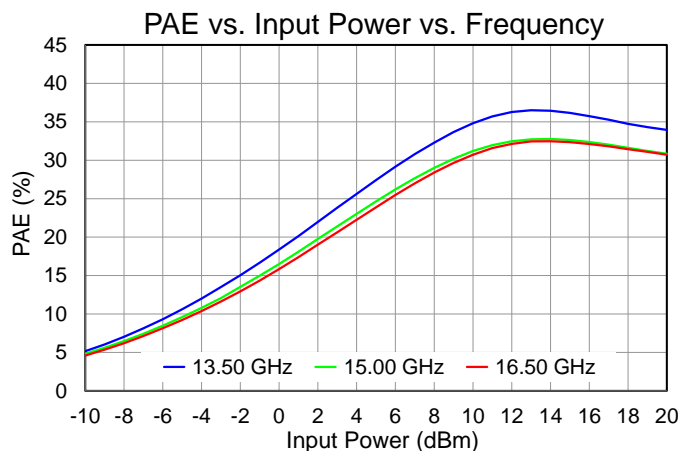
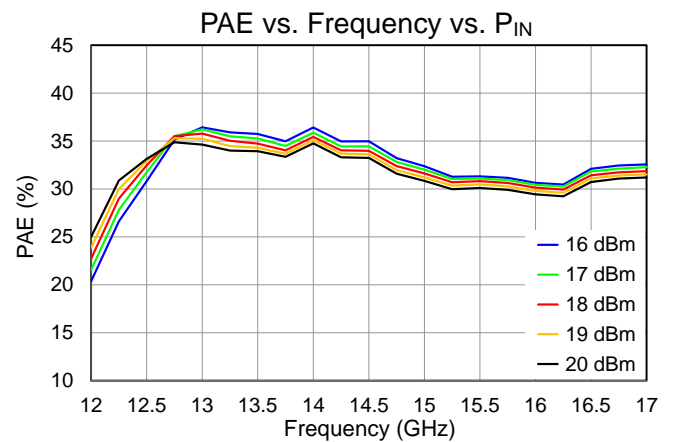
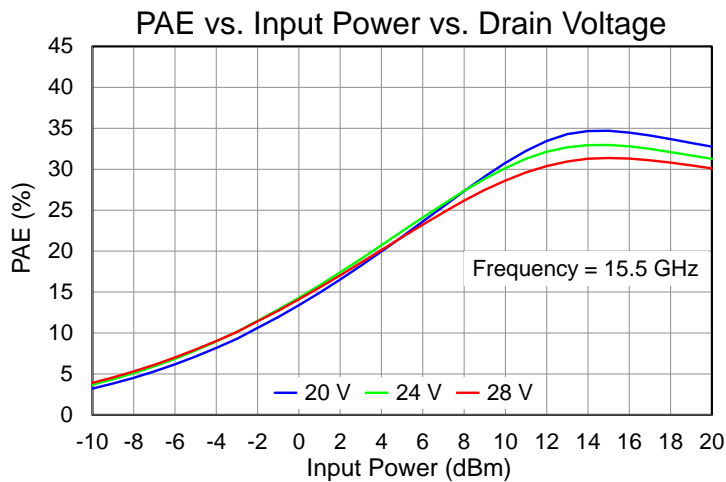
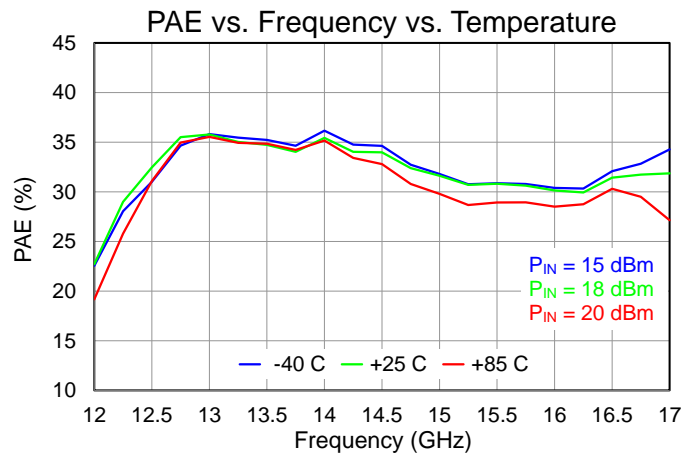
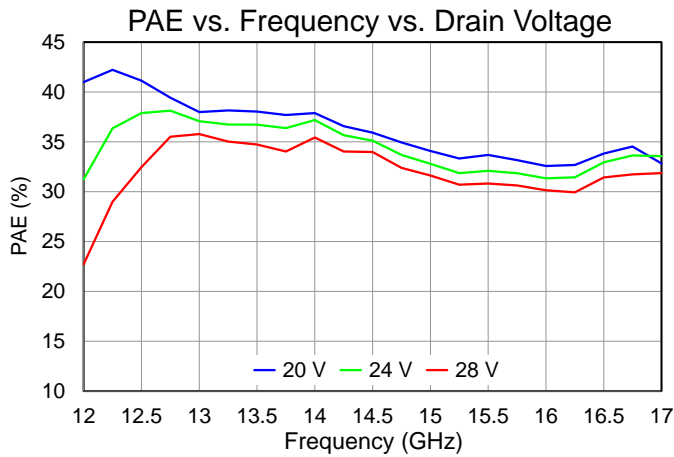
Typical Performance: CW Power Operation

Test conditions unless otherwise noted: 25 °C, $V_D = 28\text{ V}$, $I_{BQ} = 225\text{ mA}$



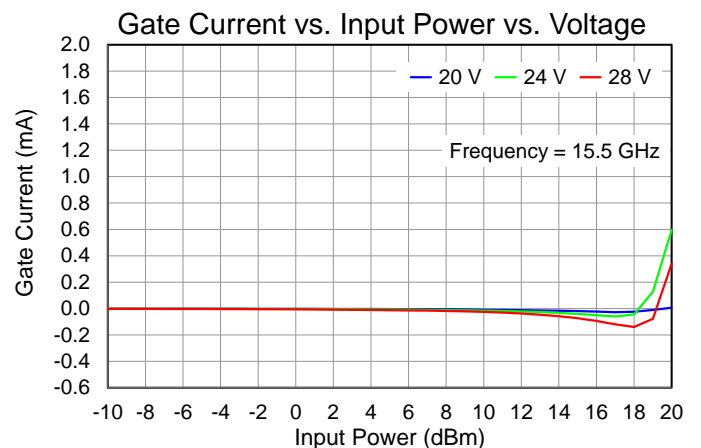
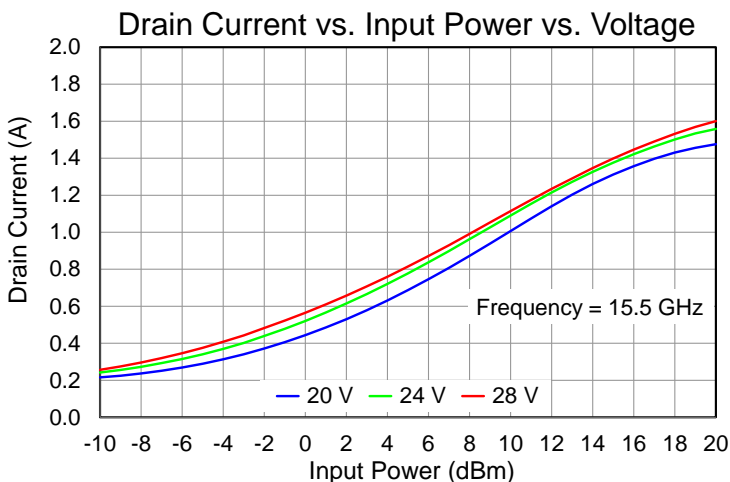
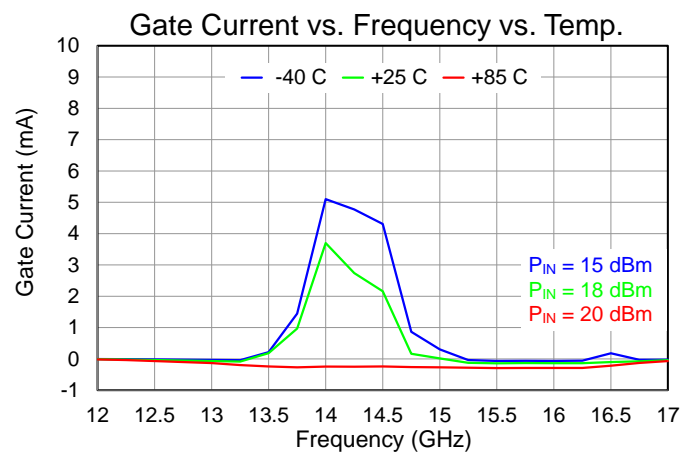
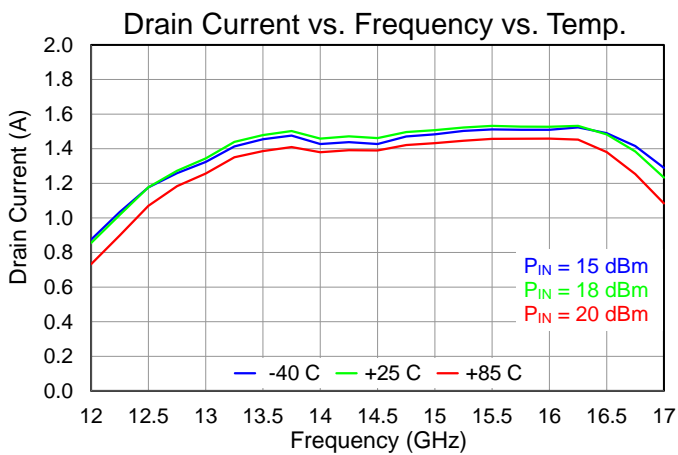
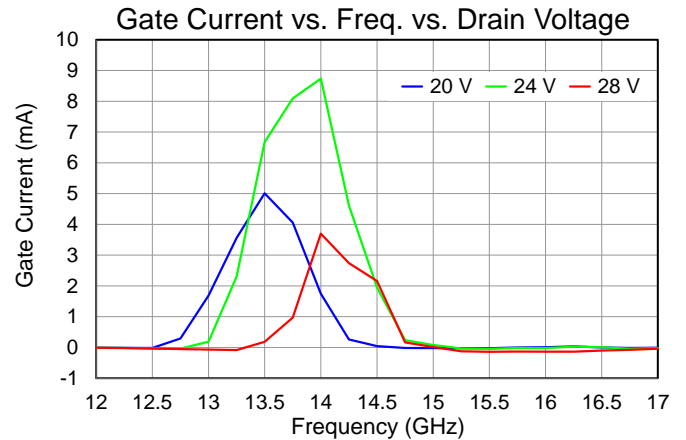
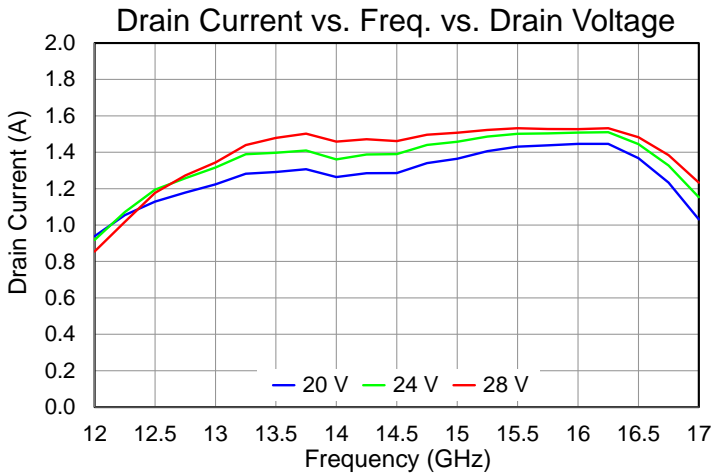
Typical Performance: CW Power Operation

Test conditions unless otherwise noted: 25 °C, $V_D = 28$ V, $I_{DQ} = 225$ mA



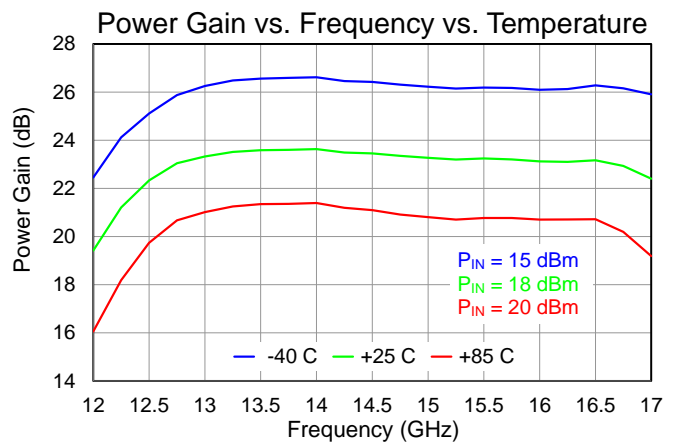
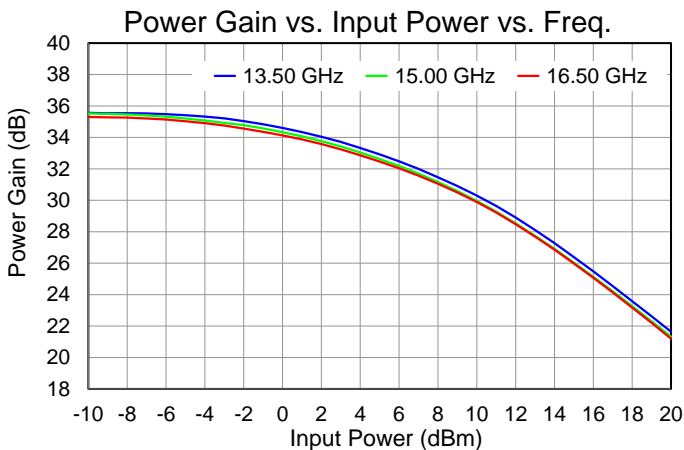
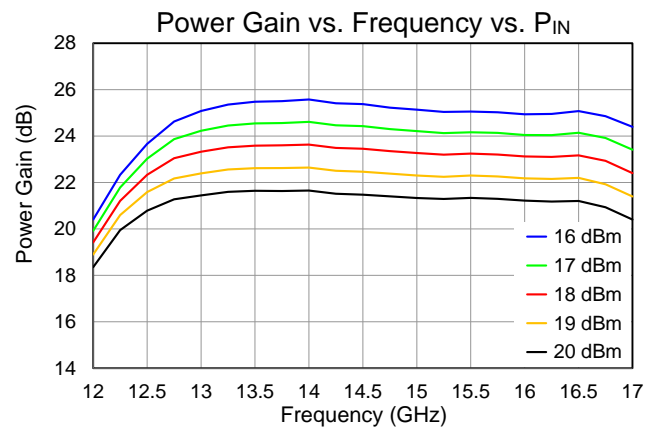
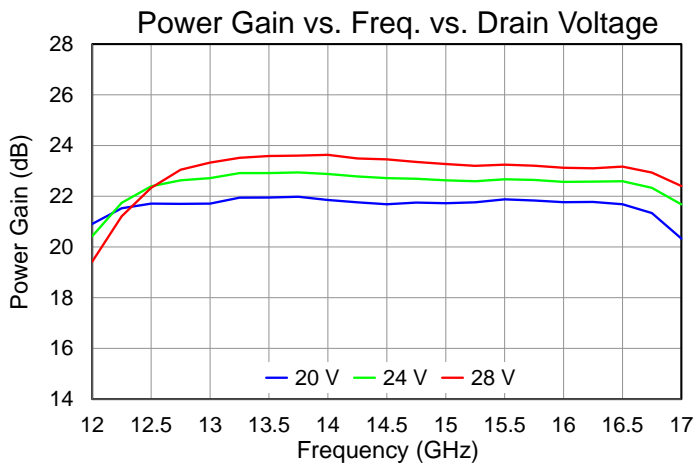
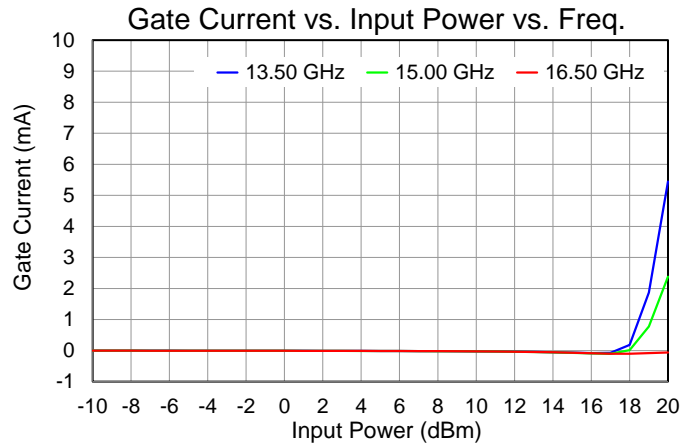
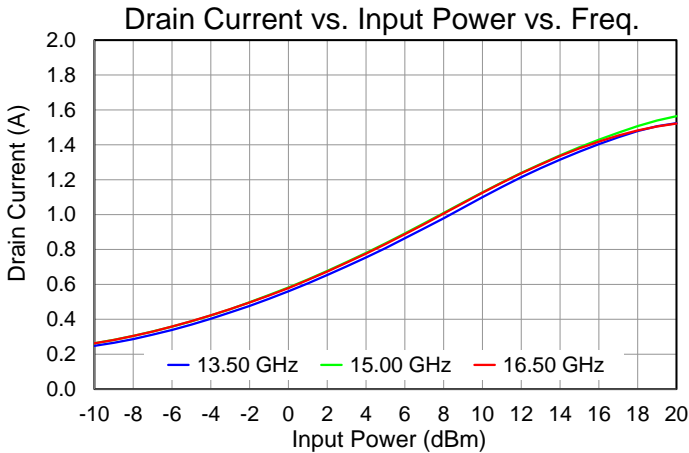
Typical Performance: CW Power Operation

Test conditions unless otherwise noted: 25 °C, $V_D = 28\text{ V}$, $I_{DQ} = 225\text{ mA}$



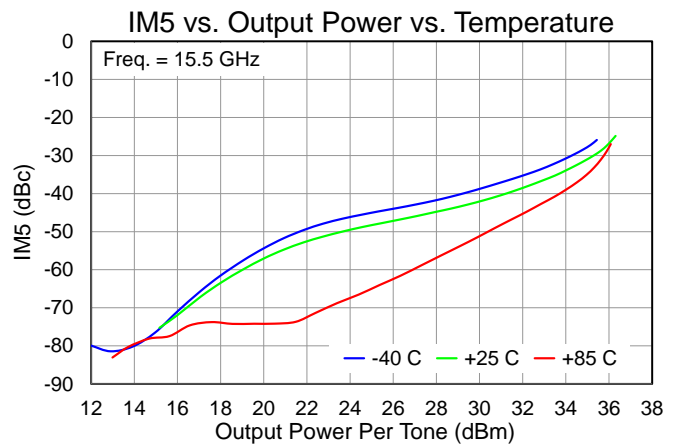
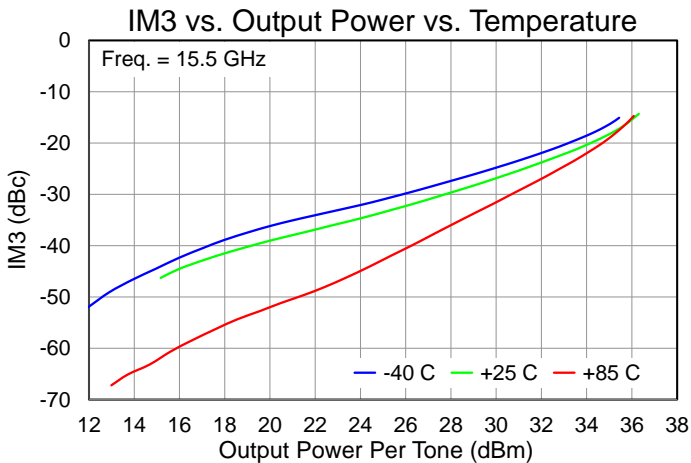
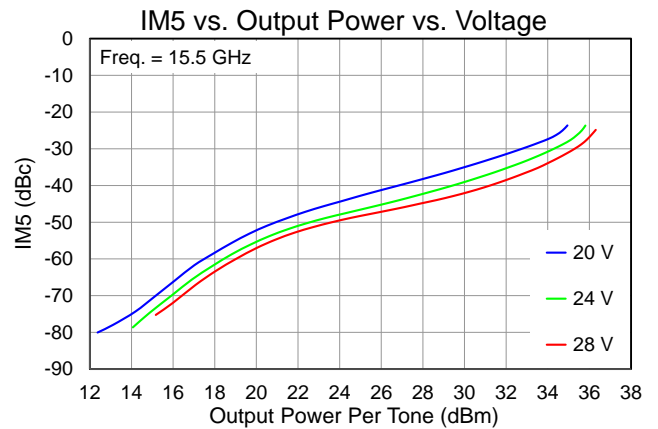
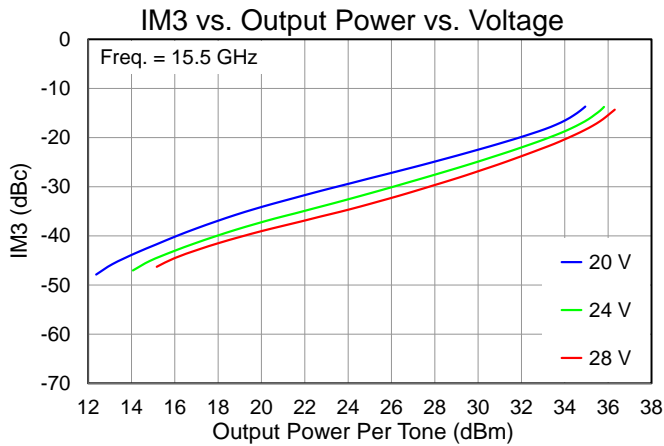
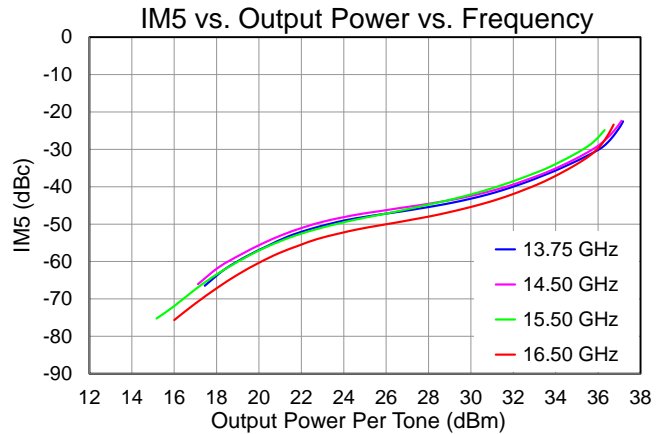
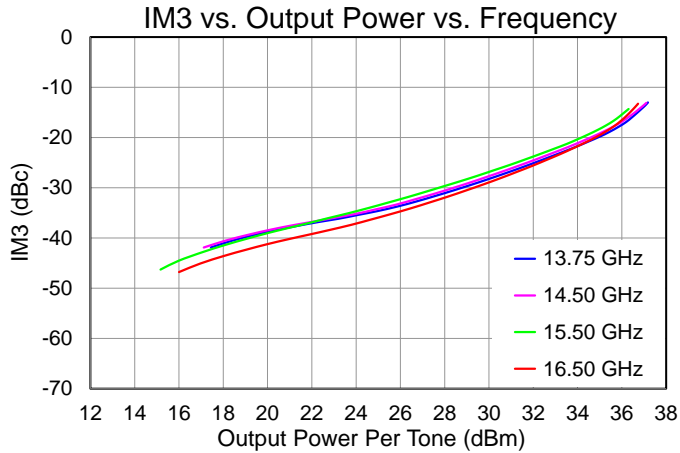
Typical Performance: CW Power Operation

Test conditions unless otherwise noted: 25 °C, $V_D = 28$ V, $I_{DQ} = 225$ mA



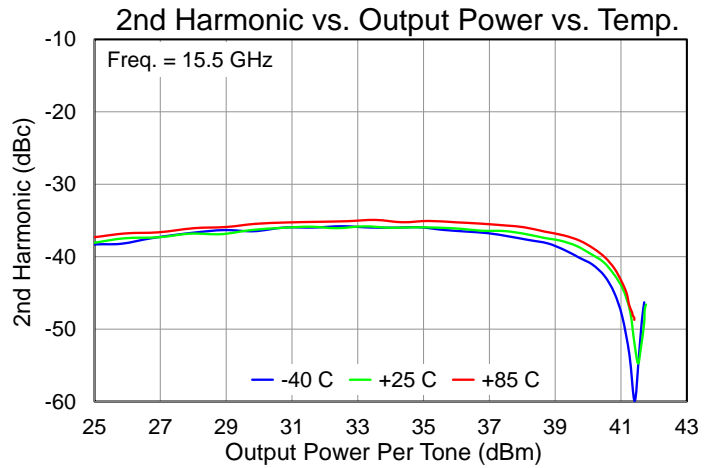
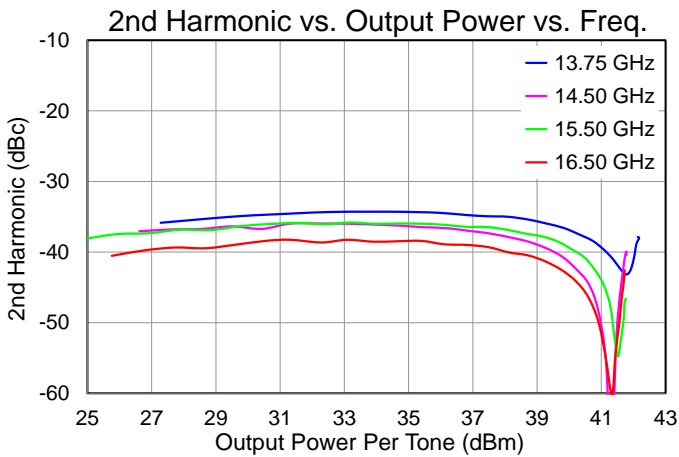
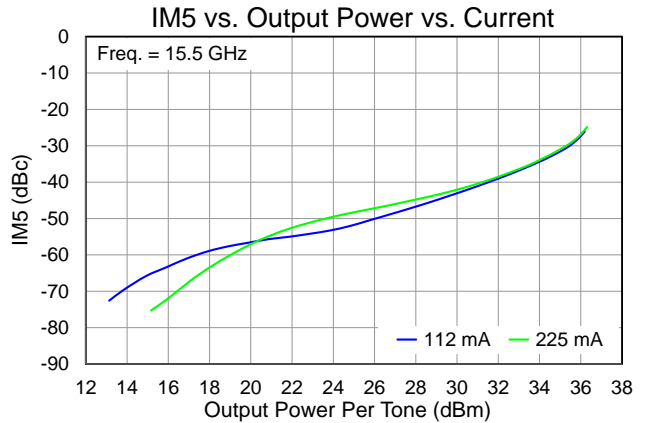
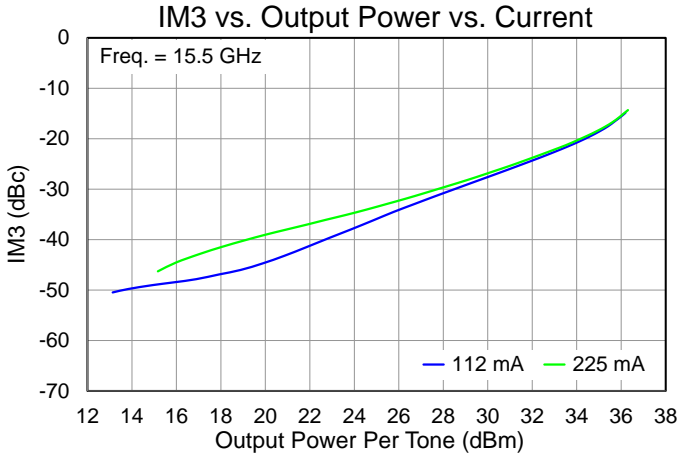
Typical Performance: Linearity

Test conditions unless otherwise noted: 25 °C, $V_D = 28$ V, $I_{DQ} = 225$ mA, CW, 1 MHz Tone Spacing



Typical Performance: Linearity

Test conditions unless otherwise noted: 25 °C, $V_D = 28$ V, $I_{DQ} = 225$ mA, CW, 1 MHz Tone Spacing



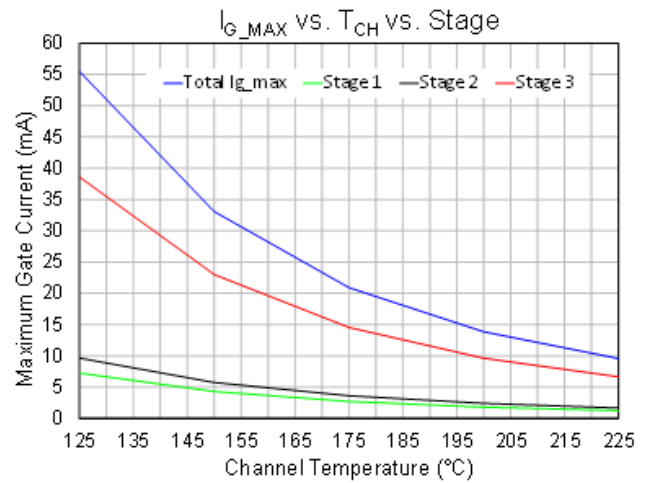
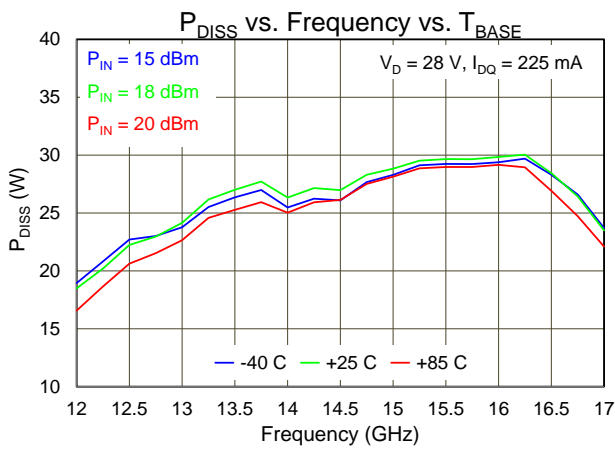
Thermal and Reliability Information

| Parameter | Test Conditions | Value | Units |
|---|--|-------|----------------------|
| Thermal Resistance (θ_{JC}) ⁽¹⁾ | $T_{base} = 85^{\circ}\text{C}$, $V_D = 28\text{ V}$, $I_{DQ} = 225\text{ mA}$ $P_{DISS} = 6.3\text{ W}$ | 2.96 | $^{\circ}\text{C/W}$ |
| Channel Temperature (T_{CH}) (no RF drive) ⁽²⁾ | | 103.7 | $^{\circ}\text{C}$ |
| Thermal Resistance (θ_{JC}) ⁽¹⁾ | $T_{base} = 85^{\circ}\text{C}$, CW, $V_D = 28\text{ V}$, $I_{DQ} = 225\text{ mA}$ Freq = 16 GHz, $I_{D_Drive} = 1.46\text{ A}$, $P_{IN} = 20\text{ dBm}$, $P_{OUT} = 40.7\text{ dBm}$, $P_{DISS} = 29.16\text{ W}$ | 2.90 | $^{\circ}\text{C/W}$ |
| Channel Temperature (T_{CH}) (with RF drive) ⁽²⁾ | | 169.4 | $^{\circ}\text{C}$ |

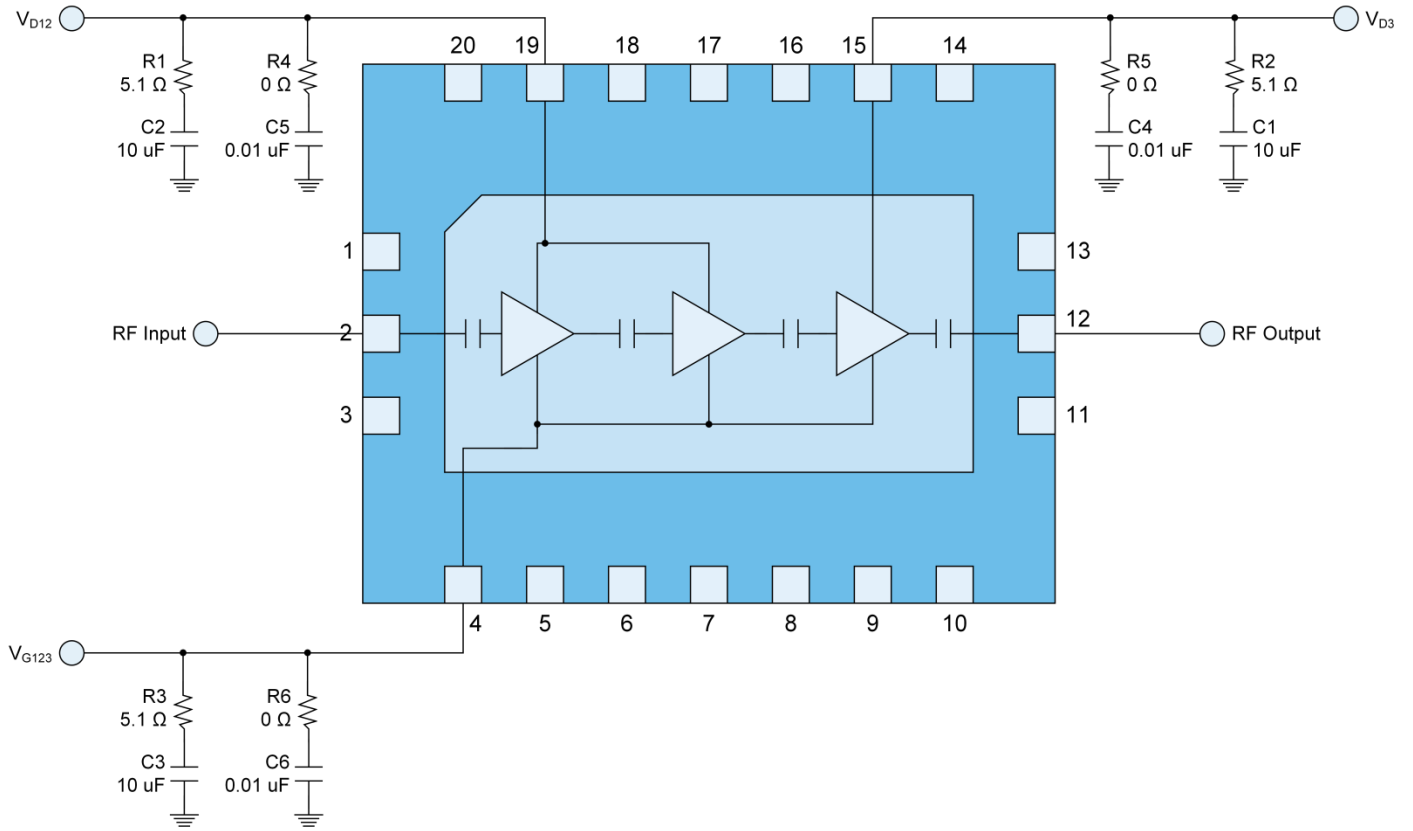
Notes:

1. Thermal resistance measured to back of package.
2. Refer to the following document: [GaN Device Channel Temperature, Thermal Resistance, and Reliability Estimates](#)

Power Dissipation and Maximum Gate Current



Application Circuit



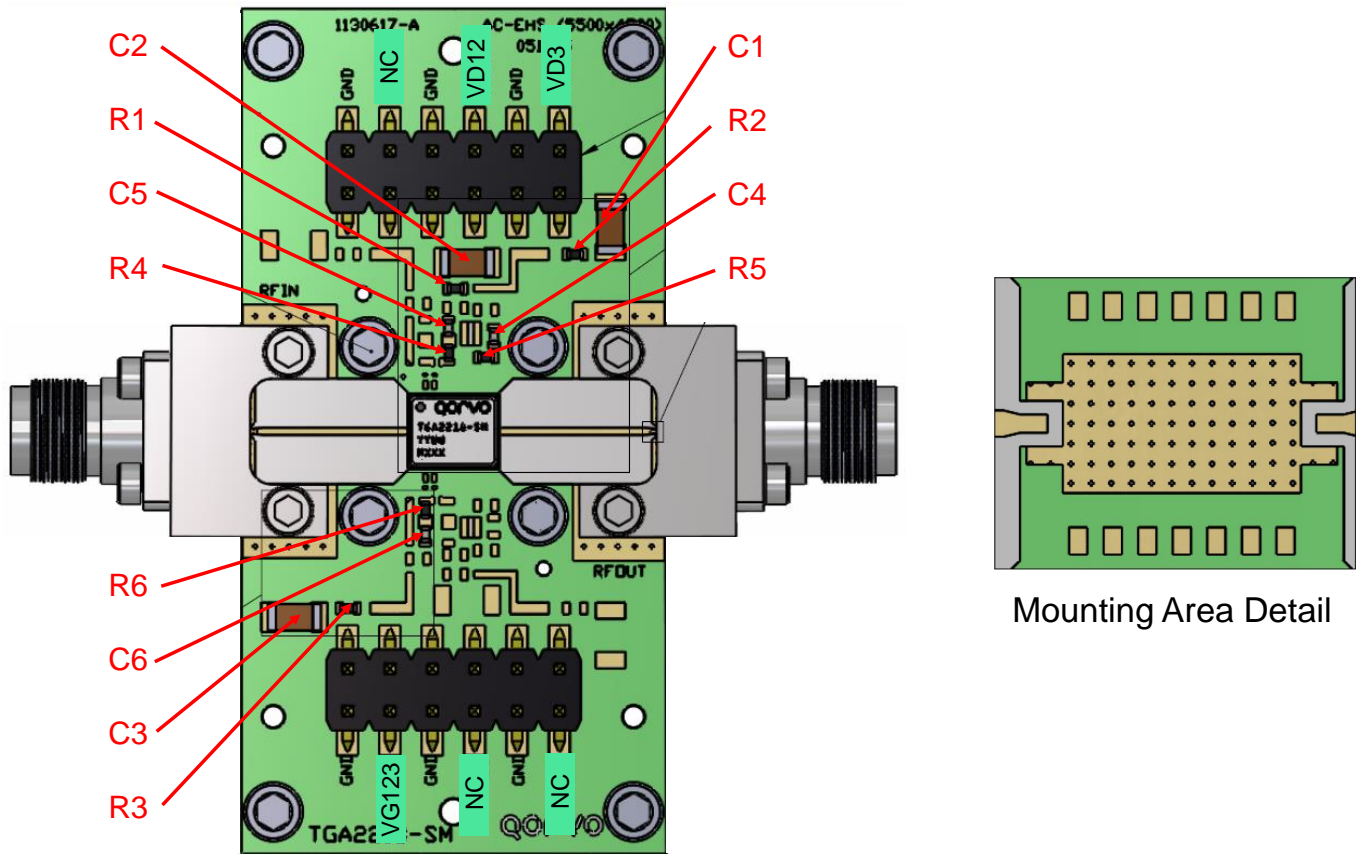
Bias-up Procedure

1. Set I_D limit to 1800 mA, I_G limit to 20 mA
2. Set V_G to -5.0 V
3. Set V_D +28 V
4. Adjust V_G more positive until $I_{DQ} = 225$ mA ($V_G \sim -2.6$ V Typical)
5. Apply RF signal

Bias-down Procedure

1. Turn off RF signal
2. Reduce V_G to -5.0 V. Ensure $I_{DQ} \sim 0$ mA
3. Set V_D to 0V
4. Turn off V_D supply
5. Turn off V_G supply

Evaluation Board and Mounting Detail

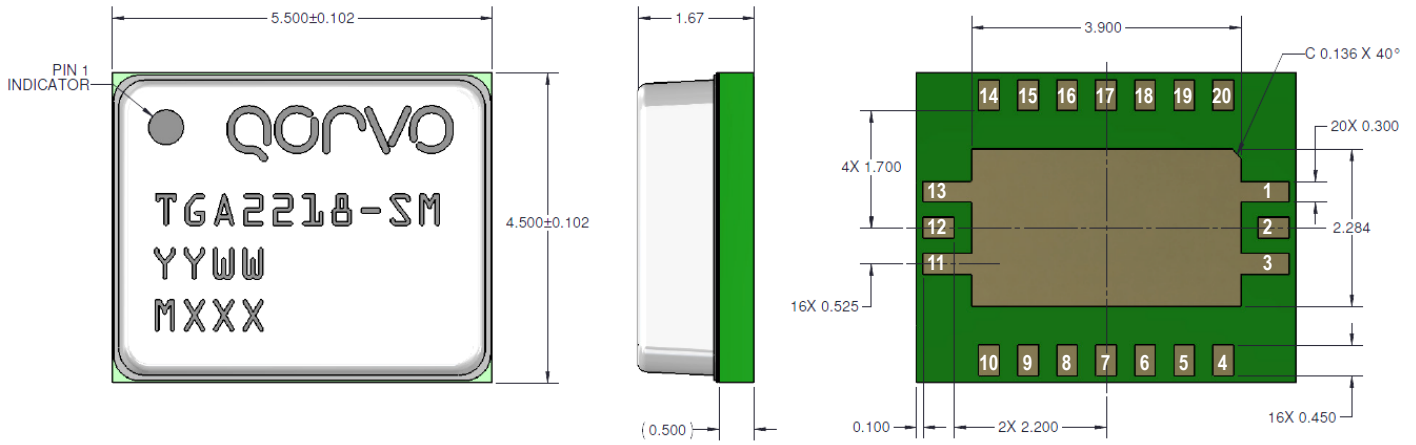


RF Layer is 0.008" thick Rogers Corp. RO40003C ($\epsilon_r = 3.35$). Metal layers are 0.5 oz. copper. The microstrip line at the connector interface is optimized for the Southwest Microwave end launch connector 1092-01A-5.

Multiple vias should be employed under package center paddle to minimize inductance and thermal resistance.

| Reference Des. | Component | Value | Manuf. | Part Number |
|----------------|-------------------|--|---------|-------------|
| C1 – C3 | Surface Mount Cap | 10 uF, $\pm 20\%$, 50 V (1206), X5R | Various | |
| C4 – C6 | Surface Mount Cap | 0.01 uF, $\pm 10\%$, 50 V (0402), X7R | Various | |
| R1 – R3 | Surface Mount Res | 5.1 Ohm, $\pm 5\%$ (0402) | Various | |
| R4 – R6 | Surface Mount Res | 0.0 Ohm, $\pm 5\%$ (0402) | Various | |

Mechanical Drawing & Pad Description

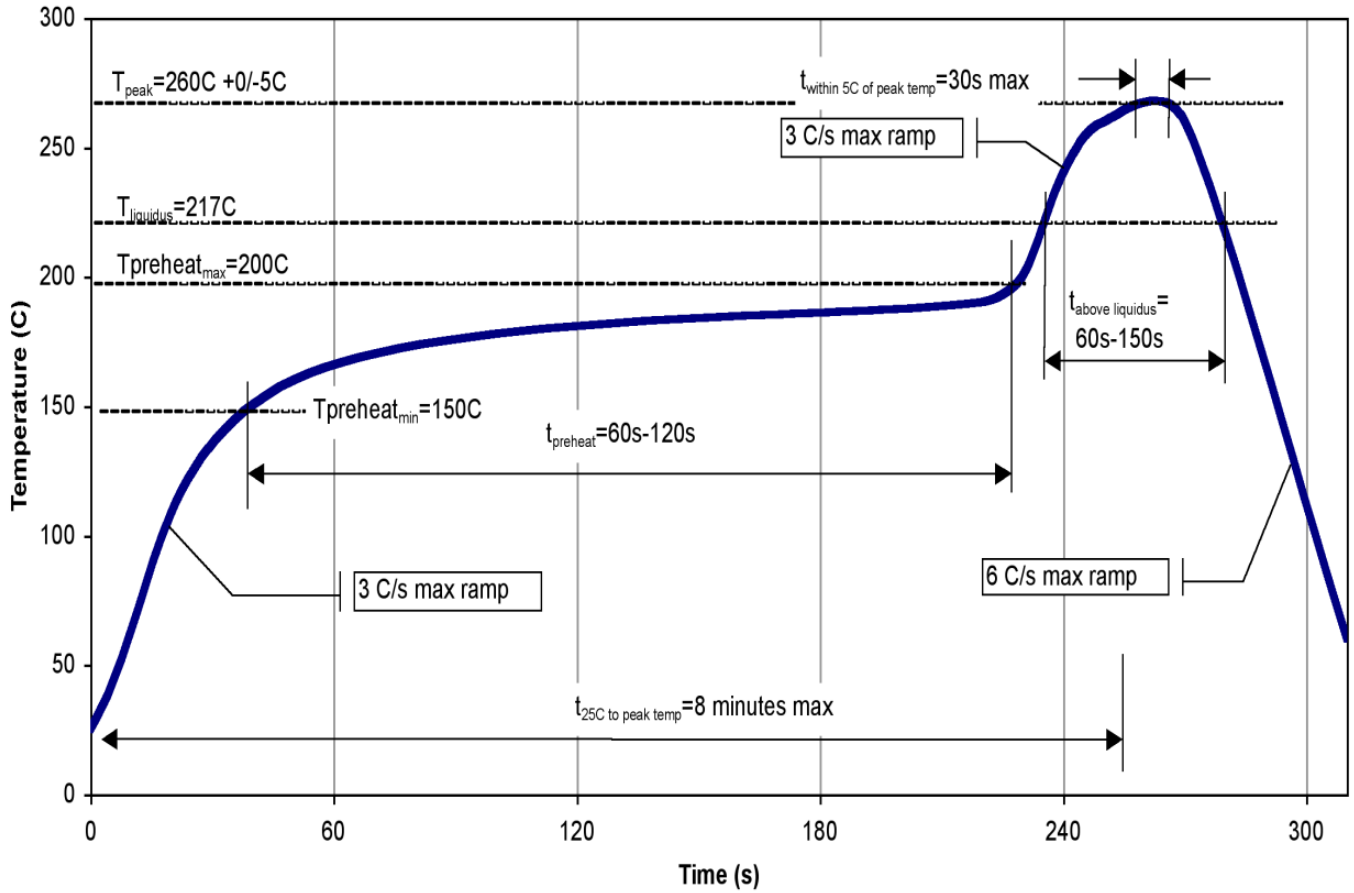


PART MARKING

TGA2218-SM: Part Number
 YY: Part Assembly Year
 WW: Part Assembly Week
 MXXX: Batch ID
 Dimensions in millimeters

| Pad Number | Symbol | Description |
|---------------------|-------------------|---|
| 1, 3, 11, 13 | GND | RF Ground (including center pad). |
| 2 | RF Input | RF Input; matched to 50 Ω; DC Blocked. |
| 4 | V _{G123} | Gate voltage stages 1-2-3. Bias network is required; see Application Circuit as an example. |
| 5-10, 14, 16-18, 20 | NC | No Connection in package; grounding may improve performance. |
| 12 | RF Output | RF Output; matched to 50Ω; DC Blocked. |
| 15 | V _{D3} | Drain voltage stage 3. Bias network is required; see Application Circuit as an example. |
| 19 | V _{D12} | Drain voltage stages 1-2. Bias network is required; see Application Circuit as an example. |

Recommended Soldering Temperature Profile



Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|--------|-----------------------|
| ESD – Human Body Model (HBM) | 1A | ANSI/ESD/JEDEC JS-001 |
| ESD – Charge Device Model (CDM) | C2A | ANSI/ESD/JEDEC JS-002 |
| MSL – Moisture Sensitivity Level | MSL3 | IPC/JEDEC J-STD-020 |



Caution!

ESD-Sensitive Device

Solderability

Compatible with the latest version of J-STD-020 Lead free solder, 260 °C. The use of no-clean solder to avoid washing after soldering is recommended.

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C15H12Br4O2) Free
- PFOS Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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Tel: 1-844-890-8163

Email: customer.support@qorvo.com

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Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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